Technical Data Sheet

Schulamid 66 GB30 H BLK968001

Polyamide 66

Product Description

30% glass bead reinforced, heat stabilized Polyamide 66

Processing Method	Injection Molding
Attribute	Good Flow; Good Surface Finish; Low Warpage; Oil Resistant
Filler/Reinforcement	Glass Bead, 30%

Typical Properties	Nominal Value	Units	Test Method
Physical			
Density, (Method A)	1.35	g/cm³	ISO 1183
Viscosity Number	140	cm³/g	ISO 307
Mechanical			
Tensile Strain at Break			
(Type 1A, 5 mm/min)	7.5	%	ISO 527-2
(Type 1A, 5 mm/min) - Conditioned	11	%	ISO 527-2
Tensile Stress at Break			
(Type 1A, 5 mm/min)	85.0	MPa	ISO 527-2
(Type 1A, 5 mm/min) - Conditioned	65.0	MPa	ISO 527-2
Tensile Modulus			
(1 mm/min, Type 1A)	4500	MPa	ISO 527-1
(1 mm/min, Type 1A) - Conditioned	2500	MPa	ISO 527-1
Impact			
Charpy Impact Strength - Notched, (23 °C, Type 1, Edgewise, Notch A)	4.0	kJ/m²	ISO 179
Charpy Impact Strength - Unnotched, (23 °C, Type 1, Edgewise)	30	kJ/m²	ISO 179
Hardness			
Ball Indentation Hardness			
(H 358/30)	185	MPa	ISO 2039-1
(H 358/30) - Conditioned	125	MPa	ISO 2039-1
Ball Pressure Test, (125 °C)	Pass		IEC 60695-10-2
Thermal			
Vicat Softening Temperature			
(B (50N), 50 °C/h)	230	°C	ISO 306
(A (10N), 50 °C/h)	235	°C	ISO 306

Deflection Temperature Under Load Unannealed (0.45 MPa), (Flatwise)	215	°C	ISO 75-2/B
Deflection Temperature Under Load Unannealed (1.80 MPa), (Flatwise)	75.0	°C	ISO 75-2/A
Electrical			
Volume Resistivity	>1.0E+13	ohm*m	IEC 62631-3-1
- Conditioned	>1.0E+10	ohm*m	IEC 62631-3-1
Comparative Tracking Index (CTI)	450	V	IEC 60112
Surface Resistivity	>1.0E+15	ohm	IEC 60093
- Conditioned	>1.0E+12	ohm	IEC 60093
Flammable			
Burning Rate			
(2.00 mm)	<100	mm/min	FMVSS 302
(2.00 mm)	<100	mm/min	ISO 3795
Glow Wire Flammability Index			
(1.5 mm) - Conditioned	650	°C	IEC 60695-2-12
(3.0 mm) - Conditioned	650	°C	IEC 60695-2-12
UL Information			
Flammability Classification			
(1.5 mm)	HB		IEC 60695-11-10, -20
(3.0 mm)	HB		IEC 60695-11-10, -20

Injection Parameters	Nominal Value	Units
Drying Time	3.0 to 4.0	hr
Drying Temperature	80	°C
Suggested Max Moisture	0.040 to 0.10	%
Processing (Melt) Temp	280 to 300	°C
Mold Temperature	60 to 120	°C